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Kind regards,

Team Nexperia

# **DISCRETE SEMICONDUCTORS**

# DATA SHEET

# **PDTA115E series** PNP resistor-equipped transistors; R1 = 100 k $\Omega$ , R2 = 100 k $\Omega$

Product data sheet Supersedes data of 2004 May 05 2004 Jul 30



# PNP resistor-equipped transistors; R1 = 100 k $\Omega$ , R2 = 100 k $\Omega$

## PDTA115E series

#### **FEATURES**

- Built-in bias resistors
- · Simplified circuit design
- Reduction of component count
- · Reduced pick and place costs.

### **APPLICATIONS**

- General purpose switching and amplification
- · Inverter and interface circuits
- Circuit driver.

#### QUICK REFERENCE DATA

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
$V_{CEO}$	collector-emitter voltage	_	-50	V
Io	output current (DC)	_	-20	mA
R1	bias resistor	100	_	kΩ
R2	bias resistor	100	_	kΩ

### **DESCRIPTION**

PNP resistor-equipped transistor (see "Simplified outline, symbol and pinning" for package details).

#### **PRODUCT OVERVIEW**

TYPE NUMBER	PAC	KAGE	MARKING CODE	NPN COMPLEMENT
ITPE NUMBER	PHILIPS	EIAJ	MARKING CODE	NPN COMPLEMENT
PDTA115EE	SOT416	SC-75	5E	PDTC115EE
PDTA115EEF	SOT490	SC-89	6B	PDTC115EEF
PDTA115EK	SOT346	SC-59	62	PDTC115EK
PDTA115EM	SOT883	SC-101	F6	PDTC115EM
PDTA115ES	SOT54 (TO-92)	SC-43	TA115E	PDTC115ES
PDTA115ET	SOT23	_	*AB <sup>(1)</sup>	PDTC115ET
PDTA115EU	SOT323	SC-70	*7C <sup>(1)</sup>	PDTC115EU

### Note

<sup>1. \* =</sup> p: Made in Hong Kong.

<sup>\* =</sup> t: Made in Malaysia.

<sup>\* =</sup> W: Made in China.

# PNP resistor-equipped transistors; R1 = 100 k $\Omega$ , R2 = 100 k $\Omega$

# PDTA115E series

# SIMPLIFIED OUTLINE, SYMBOL AND PINNING

TYPE NUMBER	CIMPLIFIED OUTLINE AND CYMPOL	PINNING		
TYPE NUMBER	SIMPLIFIED OUTLINE AND SYMBOL	PIN	DESCRIPTION	
PDTA115ES	1 R1 R2 3 MAM338	1 2 3	base collector emitter	
PDTA115EE PDTA115EEF PDTA115EK PDTA115ET PDTA115EU	3 1 R1 R2 Top view MDB271	1 2 3	base emitter collector	
PDTA115EM	2 R1 R2 R2 MDB267	1 2 3	base emitter collector	

# PNP resistor-equipped transistors; R1 = 100 k $\Omega$ , R2 = 100 k $\Omega$

# PDTA115E series

### **ORDERING INFORMATION**

TYPE NUMBER		PACKAGE					
NAME		DESCRIPTION	VERSION				
PDTA115EE	_	plastic surface mounted package; 3 leads	SOT416				
PDTA115EEF	_	plastic surface mounted package; 3 leads	SOT490				
PDTA115EK	_	plastic surface mounted package; 3 leads	SOT346				
PDTA115EM	_	leadless ultra small plastic package; 3 solder lands; body $1.0\times0.6\times0.5~\text{mm}$	SOT883				
PDTA115ES	_	plastic single-ended leaded (through hole) package; 3 leads	SOT54				
PDTA115ET	_	plastic surface mounted package; 3 leads	SOT23				
PDTA115EU	_	plastic surface mounted package; 3 leads	SOT323				

### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	-50	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	-50	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	-10	V
VI	input voltage				
	positive		_	+10	V
	negative		_	-40	V
Io	output current (DC)		_	-20	mA
I <sub>CM</sub>	peak collector current		_	-100	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C			
	SOT23	note 1	_	250	mW
	SOT54	note 1	_	500	mW
	SOT323	note 1	_	200	mW
	SOT346	note 1	_	250	mW
	SOT416	note 1	_	150	mW
	SOT490	notes 1 and 2	_	250	mW
	SOT883	notes 2 and 3	_	250	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

### **Notes**

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60  $\mu m$  copper strip line.

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# PNP resistor-equipped transistors; R1 = 100 k $\Omega$ , R2 = 100 k $\Omega$

# PDTA115E series

### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	T <sub>amb</sub> ≤ 25 °C		
	SOT23	note 1	500	K/W
	SOT54	note 1	250	K/W
	SOT323	note 1	625	K/W
	SOT346	note 1	500	K/W
	SOT416	note 1	833	K/W
	SOT490	notes 1 and 2	500	K/W
	SOT883	notes 2 and 3	500	K/W

### **Notes**

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60  $\mu m$  copper strip line.

### **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	$V_{CB} = -50 \text{ V}; I_E = 0 \text{ A}$	_	_	-100	nA
I <sub>CEO</sub>	collector-emitter cut-off current	$V_{CE} = -30 \text{ V}; I_B = 0 \text{ A}$	_	_	-1	μΑ
		$V_{CE} = -30 \text{ V}; I_{B} = 0 \text{ A};$ $T_{j} = 150 \text{ °C}$	_	_	-50	μΑ
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = -5 \text{ V}; I_C = 0 \text{ A}$	_	_	-50	μΑ
h <sub>FE</sub>	DC current gain	$V_{CE} = -5 \text{ V}; I_{C} = -5 \text{ mA}$	80	_	_	
V <sub>CEsat</sub>	collector-emitter saturation voltage	$I_C = -5 \text{ mA}; I_B = -0.25 \text{ mA}$	_	_	-150	mV
V <sub>i(off)</sub>	input-off voltage	$I_C = -100 \mu A; V_{CE} = -5 V$	_	-1.2	-0.5	V
V <sub>i(on)</sub>	input-on voltage	$I_C = -1 \text{ mA}; V_{CE} = -0.3 \text{ V}$	-3	-1.6	_	V
R1	input resistor		70	100	130	kΩ
<u>R2</u> R1	resistor ratio		0.8	1	1.2	
C <sub>c</sub>	collector capacitance	$I_E = I_e = 0 \text{ A}; V_{CB} = -10 \text{ V};$ f = 1 MHz	_	_	3	pF

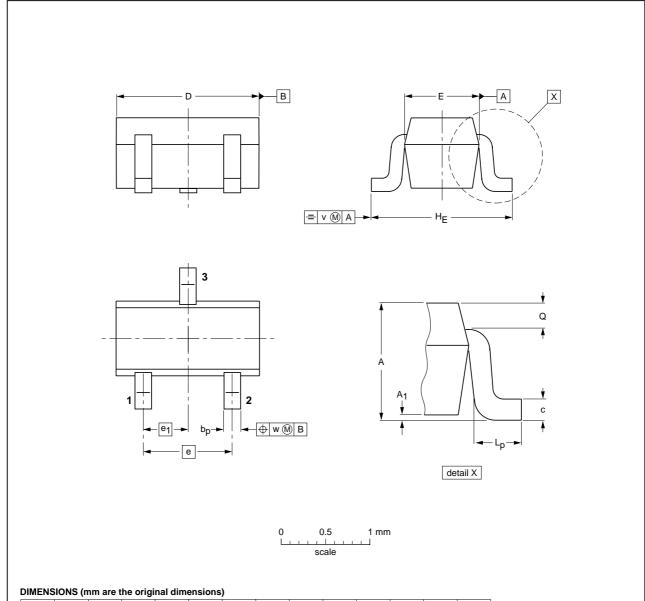
# PNP resistor-equipped transistors; $R1 = 100 \text{ k}\Omega$ , $R2 = 100 \text{ k}\Omega$

# PDTA115E series

### **PACKAGE OUTLINES**

Plastic surface-mounted package; 3 leads

**SOT416** 



DIMENS	IONS (I	nm are	the origi	nai dim	ensions)	
						-

UNIT	Α	A <sub>1</sub> max	bp	С	D	E	е	e <sub>1</sub>	HE	Lp	ø	v	w
mm	0.95 0.60	0.1	0.30 0.15	0.25 0.10	1.8 1.4	0.9 0.7	1	0.5	1.75 1.45	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
SOT416			SC-75		<del>04-11-04</del> 06-03-16

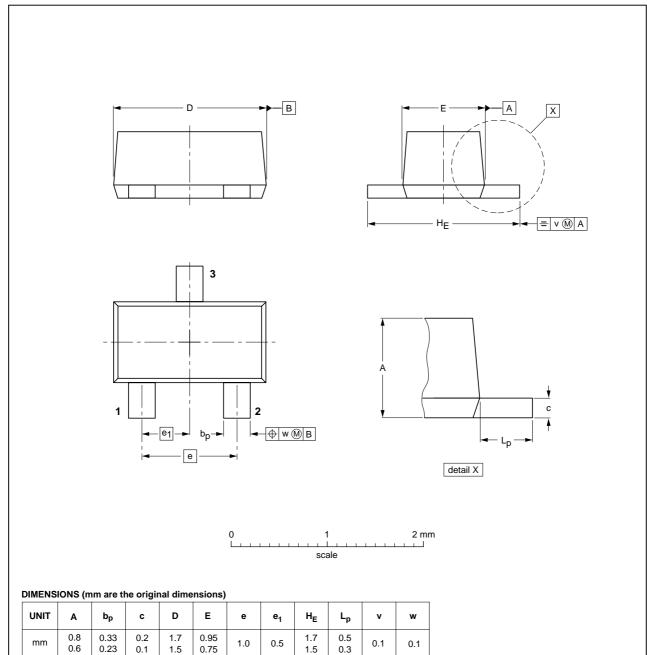
2004 Jul 30 6

# PNP resistor-equipped transistors; R1 = 100 k $\Omega$ , R2 = 100 k $\Omega$

# PDTA115E series

## Plastic surface-mounted package; 3 leads

SOT490

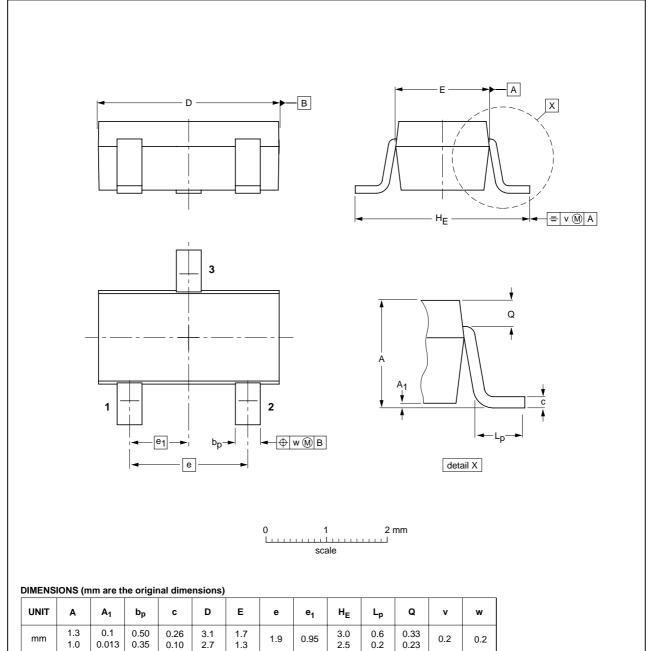


VERSION IEC JEDEC JEITA PROJECTION 95-97	OUTLINE		REFER	ENCES	 EUROPEAN	ISSUE DATE
	VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
30-09 06-03	SOT490			SC-89		<del>05-07-28</del> 06-03-16

# PNP resistor-equipped transistors; R1 = 100 k $\Omega$ , R2 = 100 k $\Omega$

# PDTA115E series

## Plastic surface-mounted package; 3 leads SOT346



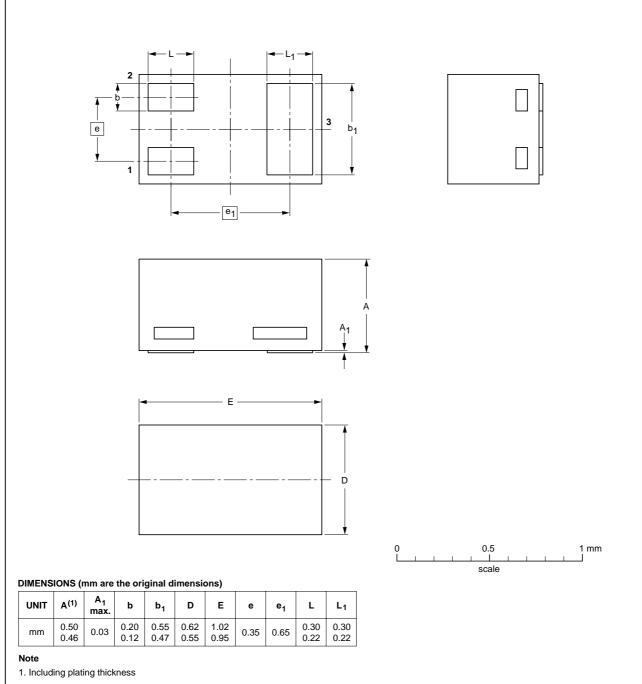
OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
SOT346		TO-236	SC-59A		<del>-04-11-11</del> 06-03-16

# PNP resistor-equipped transistors; R1 = 100 k $\Omega$ , R2 = 100 k $\Omega$

# PDTA115E series

## Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.5 mm

**SOT883** 



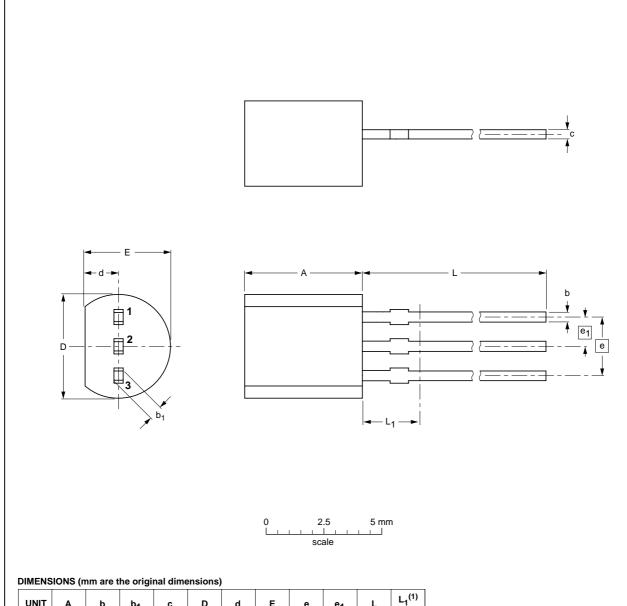
OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
SOT883			SC-101		<del>03-02-05</del> 03-04-03

# PNP resistor-equipped transistors; R1 = 100 k $\Omega$ , R2 = 100 k $\Omega$

# PDTA115E series

## Plastic single-ended leaded (through hole) package; 3 leads

SOT54



UNIT	Α	b	b <sub>1</sub>	С	D	d	E	е	e <sub>1</sub>	L	L <sub>1</sub> <sup>(1)</sup> max.	
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5	

#### Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

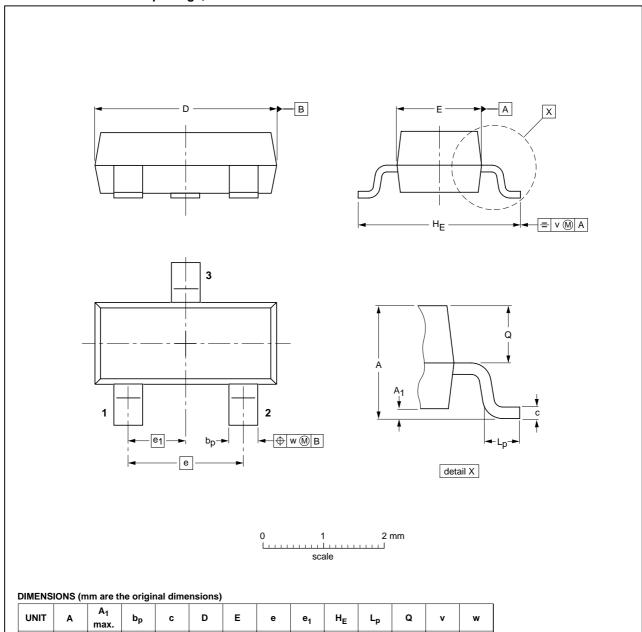
OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
SOT54		TO-92	SC-43A		<del>-04-06-28</del> 04-11-16

# PNP resistor-equipped transistors; R1 = 100 k $\Omega$ , R2 = 100 k $\Omega$

# PDTA115E series

## Plastic surface-mounted package; 3 leads

SOT23



OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
SOT23		TO-236AB			<del>-04-11-04-</del> 06-03-16

1.9

0.45

0.55

0.1

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0.48

0.38

0.15

1.1

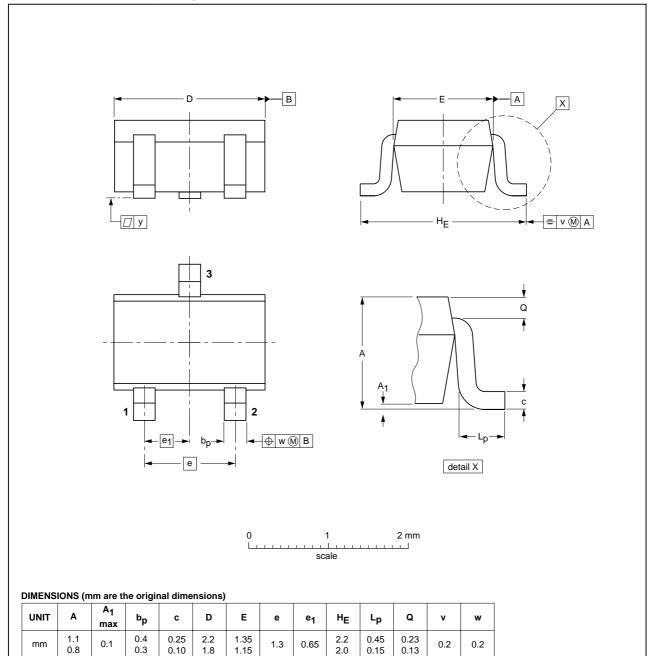
0.9

# PNP resistor-equipped transistors; R1 = 100 k $\Omega$ , R2 = 100 k $\Omega$

# PDTA115E series

## Plastic surface-mounted package; 3 leads

**SOT323** 



VERSION IEC JEDEC JEITA PROJECTION  SOT323  SC-70  O4-11-04-	OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
SO(323)	VERSION	IEC	JEDEC	JEITA	PROJECTION	1350E DATE
—	SOT323			SC-70		<del>-04-11-04</del> 06-03-16

# PNP resistor-equipped transistors; R1 = 100 k $\Omega$ , R2 = 100 k $\Omega$

## PDTA115E series

#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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# **NXP Semiconductors**

### **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

#### **Contact information**

For additional information please visit: http://www.nxp.com
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